SN54AHC374, SN74AHC374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS SCLS240I - OCTOBER 1995 - REVISED JULY 2003 Operating Range 2-V to 5.5-V V_{CC} **ESD Protection Exceeds JESD 22** . - 2000-V Human-Body Model (A114-A) **3-State Outputs Drive Bus Lines Directly** - 200-V Machine Model (A115-A) Latch-Up Performance Exceeds 250 mA Per 1000-V Charged-Device Model (C101) JESD 17 SN54AHC374 . . . J OR W PACKAGE SN54AHC374 . . . FK PACKAGE SN74AHC374... DB, DGV, DW, N, NS, OR PW PACKAGE (TOP VIEW) (TOP VIEW) ₽₽₽₽₽ 20 🛛 V_{CC} OE 19 8Q 2 1 20 19 1Q 2 3 2D 18**П** 8D 4 1D [3 18 8D 2Q 5 17 7D 2D [17 🛛 7D 4 3Q 7Q Π 6 16 2Q 🛛 5 16 7Q 3D 15 6Q 7 3Q 🛛 6 15 6Q 4D 14 6D 14 6D 3D [7 9 10 11 12 13 8 13 5D 4D 50 50 50 GND GND 9 4Q 12 5Q

description/ordering information

GND

10

11 CLK

The 'AHC374 devices are octal edge-triggered D-type flip-flops that feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels of the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74AHC374N	SN74AHC374N
	SOIC - DW	Tube	SN74AHC374DW	AHC374
	3010 - 010	Tape and reel	SN74AHC374DWR	Anc374
-40°C to 85°C	SOP – NS	Tape and reel	SN74AHC374NSR	AHC374
-40 C 10 85 C	SSOP – DB	Tape and reel	SN74AHC374DBR	HA374
	TSSOP – PW	Tube	SN74AHC374PW	HA374
	1330F - FW	Tape and reel	SN74AHC374PWR	11/13/4
	TVSOP – DGV	Tape and reel	SN74AHC374DGVR	HA374
	CDIP – J	Tube	SNJ54AHC374J	SNJ54AHC374J
–55°C to 125°C	C to 125°C CFP – W Tube SNJ		SNJ54AHC374W	SNJ54AHC374W
	LCCC – FK	Tube	SNJ54AHC374FK	SNJ54AHC374FK

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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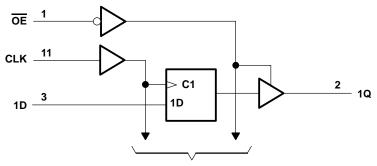
description/ordering information (continued)

OE does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

	FUNCTION TABLE (each flip-flop)									
	INPUTS	OUTPUT								
OE	CLK	D	Q							
L	\uparrow	Н	Н							
L	\uparrow	L	L							
L	H or L	Х	Q ₀							
н	Х	Х	Z							

logic diagram (positive logic)



To Seven Other Channels



SN54AHC374, SN74AHC374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1)		–0.5 V to 7 V
Output voltage range, V _O (see Note 1)		
Input clamp current, I _{IK} (V _I < 0)		
Output clamp current, I_{OK} (V _O < 0 or V _O > V _C		
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$		±25 mA
Continuous current through V _{CC} or GND		±75 mA
Package thermal impedance, θ_{JA} (see Note 2)): DB package	
	DGV package	92°C/W
	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
	PW package	83°C/W
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54A	HC374	SN74A	HC374		
			MIN	MAX	MIN	MAX	UNIT	
VCC	Supply voltage		2	5.5	2	5.5	V	
		$V_{CC} = 2 V$	1.5		1.5			
VIH	High-level input voltage	$V_{CC} = 3 V$	2.1		2.1		V	
		V _{CC} = 5.5 V	3.85		3.85			
		$V_{CC} = 2 V$		0.5		0.5		
VIL	Low-level input voltage	$V_{CC} = 3 V$		0.9		0.9	V	
		$V_{CC} = 5.5 V$		1.65		1.65		
VI	Input voltage		0	5.5	0	5.5	V	
VO	Output voltage		0	VCC	0	VCC	V	
		$V_{CC} = 2 V$		-50		-50	μA	
IОН	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		-4		-4	mA	
		V_{CC} = 5 V ± 0.5 V		-8		-8		
		$V_{CC} = 2 V$		50		50	μA	
IOL	Low-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4		4	~ ^	
		$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		8		8	mA	
A+/ A>/	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		100 100		100	ns/V	
$\Delta t / \Delta v$	Input transition rise or fall rate $V_{CC} = 5 V \pm 0.5 V$			20		20		
Тд	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SN54AHC374, SN74AHC374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vee	T	4 = 25°C	;	SN54AHC374		SN74AHC374		UNIT
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V	1.9	2		1.9		1.9		
	I _{OH} = -50 μA	3 V	2.9	3		2.9		2.9		
VOH		4.5 V	4.4	4.5		4.4		4.4		V
	I _{OH} = -4 mA	3 V	2.58			2.48		2.48		
	I _{OH} = -8 mA	4.5 V	3.94			3.8		3.8		
		2 V			0.1		0.1		0.1	
	I _{OL} = 50 μA	3 V			0.1		0.1		0.1	
VOL		4.5 V			0.1		0.1		0.1	V
	I _{OL} = 4 mA	3 V			0.36		0.5		0.44	
	I _{OL} = 8 mA	4.5 V			0.36		0.5		0.44	
lj	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1*		±1	μA
I _{OZ}	$V_{O} = V_{CC}$ or GND	5.5 V			±0.25		±2.5		±2.5	μA
ICC	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			4		40		40	μA
Ci	$V_I = V_{CC}$ or GND	5 V		4	10				10	pF
Co	$V_{O} = V_{CC}$ or GND	5 V		6						pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

		T _A = 25°C		SN54A	HC374	SN74A	SN74AHC374	
			MAX	MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration, CLK high or low	5		5.5		5.5		ns
t _{su}	Setup time, data before CLK1	4.5		4		4		ns
th	Hold time, data after CLK^\uparrow	2		2		2		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

		T _A = 2	T _A = 25°C		SN54AHC374 SN74A			UNIT
		MIN MAX		MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration, CLK high or low	5		5		5		ns
t _{su}	Setup time, data before CLK [↑]	3		3		3		ns
th	Hold time, data after CLK↑	2		2		2		ns



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switching characteristics over recommended operating free-air temperature range,
V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T _A = 25°C			SN54A	HC374	SN74A				
PARAMETER	(INPUT)	(OUTPUT)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT		
4			C _L = 15 pF	80*	130*		70*		70		MHz		
f _{max}			C _L = 50 pF	55	85		50		50				
^t PLH	CLK	Q	C _I = 15 pF		8.1*	12.7*	1*	15*	1	15	ns		
^t PHL	ULK	Q	CL = 15 pr		8.1*	12.7*	1*	15*	1	15	115		
^t PZH		Q	Ci – 15 pF		7.1*	11*	1*	13*	1	13	ns		
^t PZL	OE	Q	C _L = 15 pF		7.1*	11*	1*	13*	1	13	115		
^t PHZ	OE	0	C _I = 15 pF		7.5*	10.5*	1*	12.5*	1	12.5	ns		
^t PLZ	OE	Q	CL = 15 pr		7.5*	10.5*	1*	12.5*	1	12.5	115		
^t PLH	CLK	0	$C_{1} = 50 \text{ pF}$		10.6	16.2	1	18.5	1	18.5	ns		
^t PHL	OLK	Q	Q C _L = 50 pF		10.6	16.2	1	18.5	1	18.5	115		
^t PZH		0	C _I = 50 pF		9.6	14.5	1	16.5	1	16.5	ns		
^t PZL	<u>OE</u> Q	Q	CL = 30 pr		9.6	14.5	1	16.5	1	16.5	115		
^t PHZ	OE	Q	C ₁ = 50 pF		10.2	14	1	16	1	16	ns		
^t PLZ	0E	Q	Q	У	$\odot_{L} = 30 \text{ pr}$		10.2	14	1	16	1	16	115
^t sk(o)			CL = 50 pF			1.5**				1.5	ns		

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

** On products compliant to MIL-PRF-38535, this parameter does not apply.

switching characteristics over recommended operating free-air temperature range,
V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T	₄ = 25°C	;	SN54A	HC374	SN74A	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
4			CL = 15 pF	130*	185*		110*		110		MHz
f _{max}			CL = 50 pF	85	120		75		75		IVITIZ
^t PLH	CLK	Q	Ci – 15 pF		5.4*	8.1*	1*	9.5*	1	9.5	-
^t PHL		Q	C _L = 15 pF		5.4*	8.1*	1*	9.5*	1	9.5	ns
^t PZH	ŌĒ	Q	C _L = 15 pF		5.1*	7.6*	1*	9*	1	9	ns
^t PZL		Q	CL = 15 pr		5.1*	7.6*	1*	9*	1	9	115
^t PHZ	<u></u>	Q	C _L = 15 pF		4.6*	6.8*	1*	8*	1	8	ns
^t PLZ	ŌE	Q	CL = 15 pr		4.6*	6.8*	1*	8*	1	8	115
^t PLH	CLK	Q	C _L = 50 pF		6.9	10.1	1	11.5	1	11.5	ns
^t PHL	OLK	Ŷ	CL = 30 pr		6.9	10.1	1	11.5	1	11.5	115
^t PZH	<u>-</u>	Q	C _I = 50 pF		6.6	9.6	1	11	1	11	ns
^t PZL	OE	v	CL = 30 pr		6.6	9.6	1	11	1	11	115
^t PHZ	\overline{OE} Q $C_L = 50 pF$	0	$C_{1} = 50 \text{ pF}$		6.1	8.8	1	10	1	10	
^t PLZ		ý	CL = 50 pr		6.1	8.8	1	10	1	10	ns
^t sk(o)			CL = 50 pF			1**				1	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

** On products compliant to MIL-PRF-38535, this parameter does not apply.



SN54AHC374, SN74AHC374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS SCLS240I – OCTOBER 1995 – REVISED JULY 2003

noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25^{\circ}C (see Note 4)

	SN	UNIT		
				UNIT
Quiet output, maximum dynamic V _{OL}		0.5	1	V
Quiet output, minimum dynamic V _{OL}		-0.5	-0.8	V
Quiet output, minimum dynamic V _{OH}	4			V
High-level dynamic input voltage	3.5			V
Low-level dynamic input voltage			1.5	V
	Quiet output, minimum dynamic V _{OL} Quiet output, minimum dynamic V _{OH} High-level dynamic input voltage	PARAMETER MIN Quiet output, maximum dynamic V _{OL} Quiet output, minimum dynamic V _{OL} Quiet output, minimum dynamic V _{OH} 4 High-level dynamic input voltage 3.5	PARAMETER MIN TYP Quiet output, maximum dynamic V _{OL} 0.5 Quiet output, minimum dynamic V _{OL} -0.5 Quiet output, minimum dynamic V _{OH} 4 High-level dynamic input voltage 3.5	MIN TYP MAX Quiet output, maximum dynamic V _{OL} 0.5 1 Quiet output, minimum dynamic V _{OL} -0.5 -0.8 Quiet output, minimum dynamic V _{OH} 4 - High-level dynamic input voltage 3.5 -

NOTE 4: Characteristics are for surface-mount packages only.

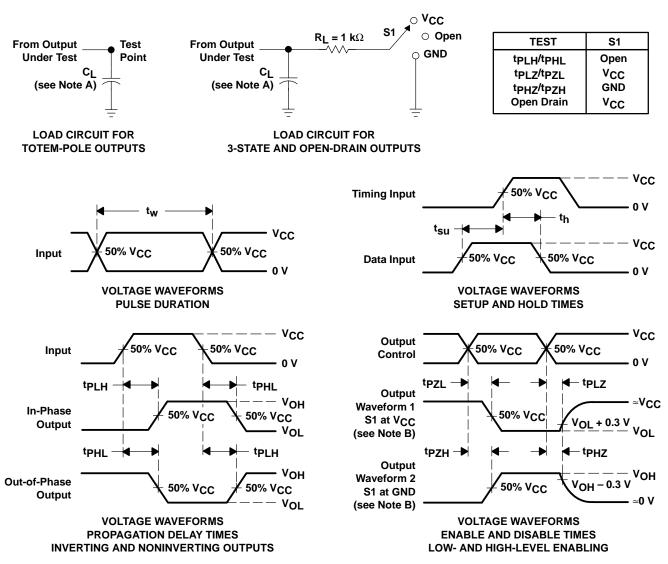
operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	No load, f = 1 MHz	32	pF



SN54AHC374, SN74AHC374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
5962-9686401Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-9686401QRA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
5962-9686401QSA	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC
SN74AHC374DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74AHC374DBR	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AHC374DGVR	ACTIVE	TVSOP	DGV	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHC374DW	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74AHC374DWR	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74AHC374N	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AHC374NSR	ACTIVE	SO	NS	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AHC374PW	ACTIVE	TSSOP	PW	20	70	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHC374PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74AHC374PWR	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54AHC374FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AHC374J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AHC374W	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM



30-Mar-2005

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20



MLCC006B - OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

DGV (R-PDSO-G**)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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